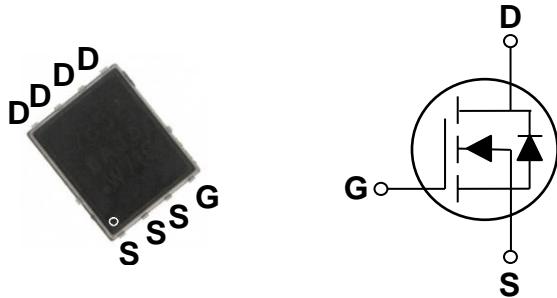


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
150V	65mΩ	15A

### Features

- 150V, 15A, RDS(ON) = 65mΩ @ VGS = 10V
- VGS Guarantee  $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	150	V
V <sub>GС</sub>	Gate-Source Voltage	$\pm 25$	V
I <sub>D</sub>	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	15	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	9.5	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	60	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	242	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	22	A
P <sub>D</sub>	Power Dissipation ( $T_c=25^\circ\text{C}$ )	135	W
	Power Dissipation – Derate above $25^\circ\text{C}$	1.08	W/ $^\circ\text{C}$
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.92	$^\circ\text{C}/\text{W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	150	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.08	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =120V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =96V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	30	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±25V , V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>Ds(ON)</sub>	Static Drain-Source On-Resistance <sup>3</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =6A	---	52	65	mΩ
		V <sub>GS</sub> =6V , I <sub>D</sub> =4A	---	65	90	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	3	4	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-2.5	---	mV/°C

**Dynamic and switching Characteristics**

Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =4A	---	30	45	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	8.7	14	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	8	15	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =6Ω I <sub>D</sub> =1A	---	14.5	28	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	19.2	18	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	33.6	60	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	22.8	25	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , F=1MHz	---	1790	3000	pF
C <sub>oss</sub>	Output Capacitance		---	160	300	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	82	160	
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V , V <sub>DS</sub> =0V , F=1MHz	---	1.4	2.8	Ω

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	15	A
I <sub>SM</sub>	Pulsed Source Current		---	---	30	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C V <sub>GS</sub> =0V,I <sub>s</sub> =1A , dI/dt=100A/μs T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>		---	---	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge <sup>2</sup>	T <sub>J</sub> =25°C	---	---	---	nC

Note :

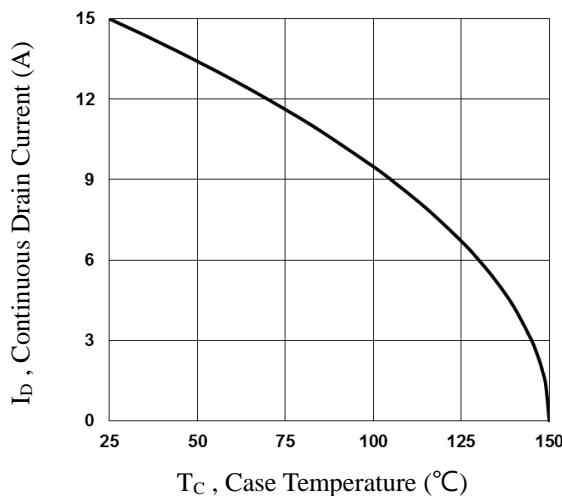
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=-50V,V<sub>GS</sub>=-10V,L=1mH,I<sub>s</sub>=-22A.,R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



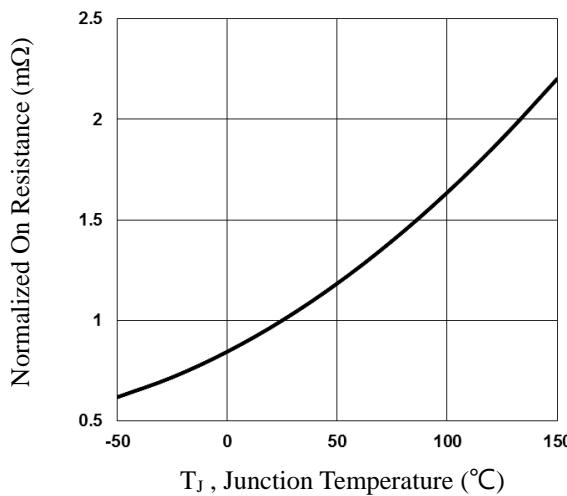
STEIF POWER  
TECHNOLOGY

150V N-Channel MOSFETs

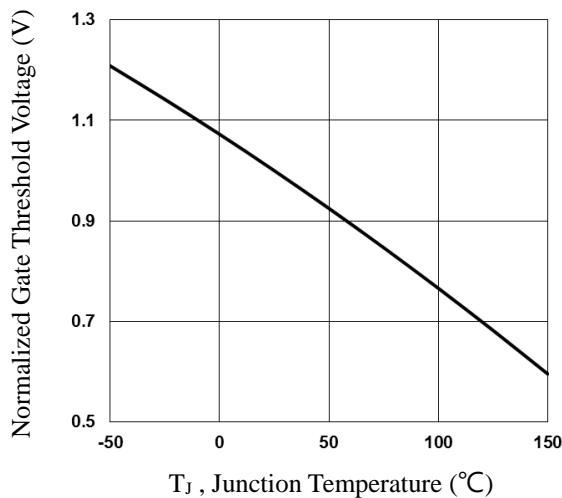
**SPC30N15X**



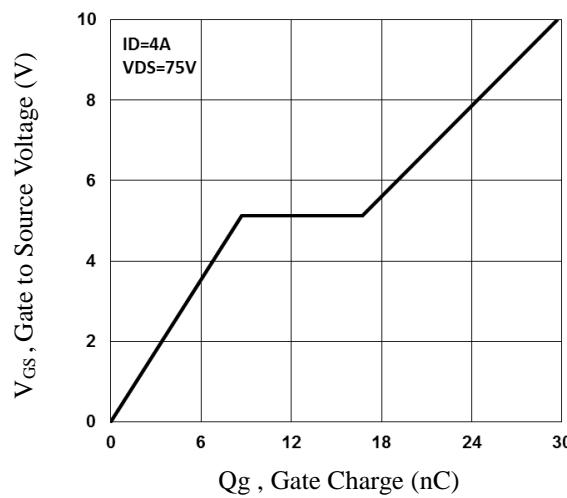
**Fig.1 Continuous Drain Current vs.  $T_C$**



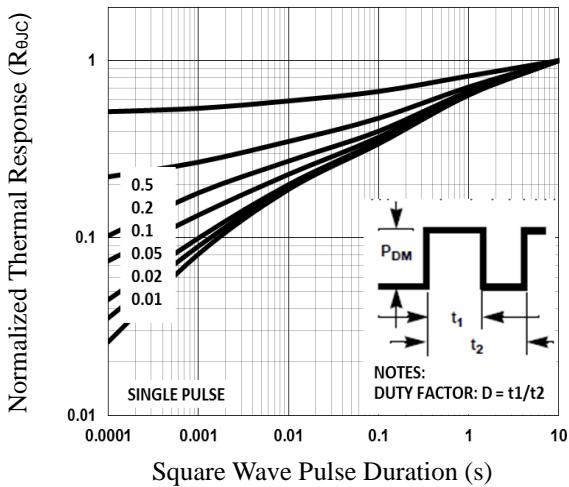
**Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$**



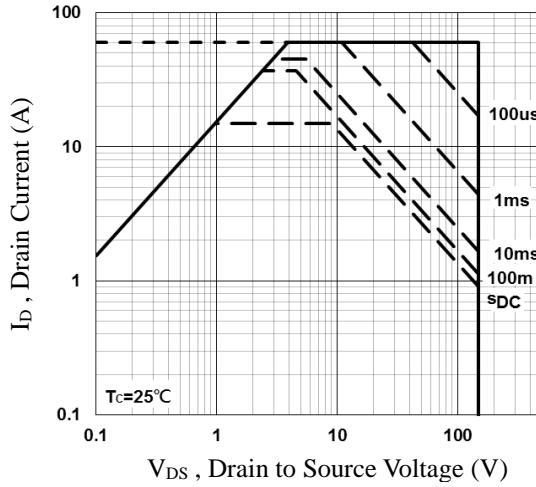
**Fig.3 Normalized V<sub>th</sub> vs.  $T_J$**



**Fig.4 Gate Charge Characteristics**



**Fig.5 Normalized Transient Impedance**



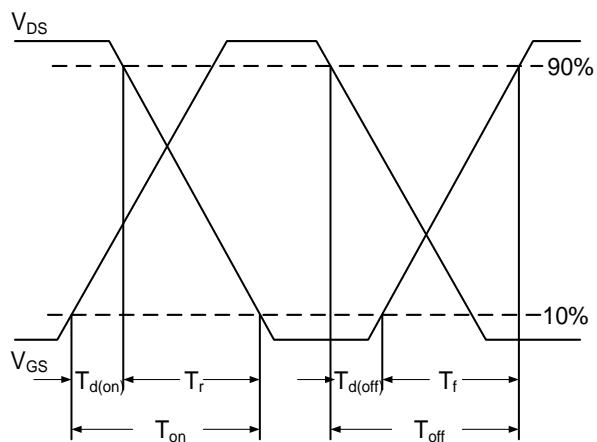
**Fig.6 Maximum Safe Operation Area**



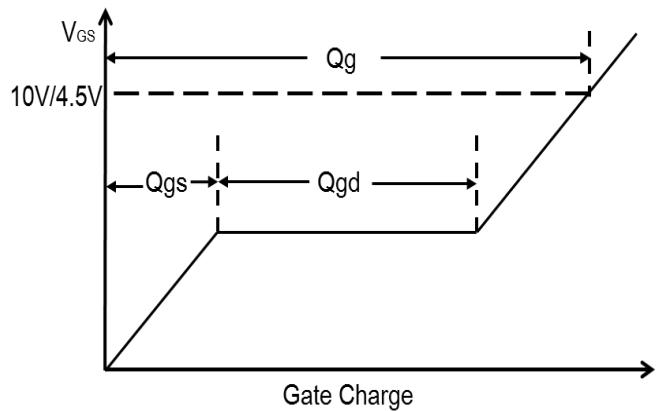
STEIFPOWER  
TECHNOLOGY

150V N-Channel MOSFETs

**SPC30N15X**



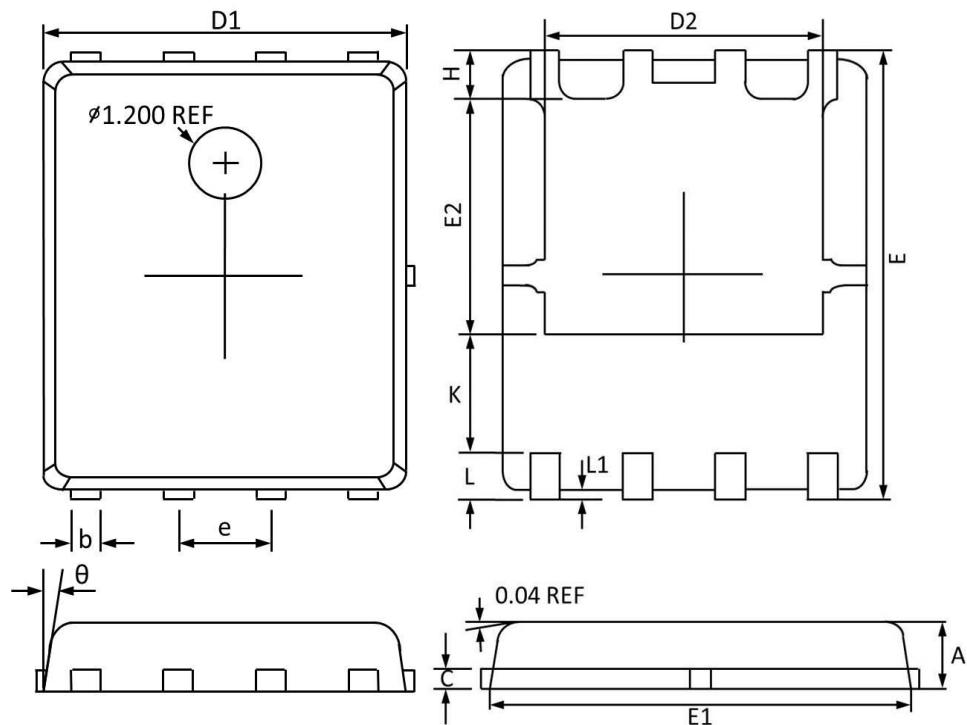
**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**



## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°